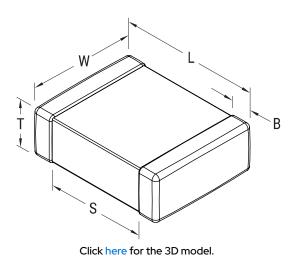




ESD SMD Comm X7R, Ceramic, 0.022 uF, 20%, 63 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 1206, 1.5 mm



General Information	
Series	ESD SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	17 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
Т	0.78mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

nip Size	1206
	3.2mm +/-0.2mm
	1.6mm +/-0.2mm
	0.78mm +/-0.10mm
	1.5mm MIN
	0.5mm +/-0.25mm
ackaging Specifications	

Specifications	
Capacitance	0.022 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	63 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	157.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0 Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	45.4545 GOhms

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

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